Features

- Advanced Trench Process Technology
- Low Threshold Voltage
- Fast Switching Speed
- Epoxy Meets UL 94 V-0 Flammability Rating
- Moisture Sensitivity Level 1
- Halogen Free. “Green” Device (Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

N-Channel MOSFET

Maximum Ratings

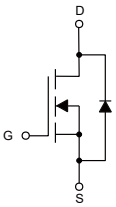
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature: -55°C to +150°C
- Thermal Resistance: 115°C/W Junction to Ambient(Note2)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	±20	V
Drain Current-Continuous	TA=25°C	I_D	0.34	A
	TA=100°C		0.22	
Pulsed Drain Current		I_{DM}	2	A
Power Dissipation		P_D	1.08	W

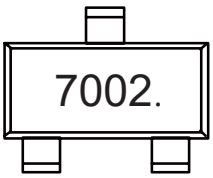
Note:

1. Halogen free "Green” products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C

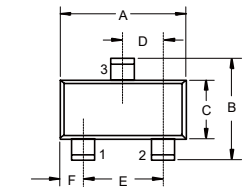
Internal Structure and Marking Code

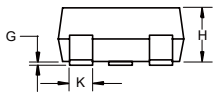


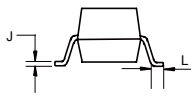
1. GATE
2. SOURCE
3. DRAIN



SOT-23

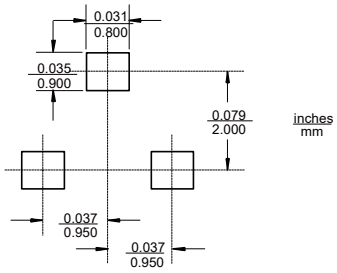






DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.110	0.120	2.80	3.04	
B	0.083	0.104	2.10	2.64	
C	0.047	0.055	1.20	1.40	
D	0.034	0.041	0.85	1.05	
E	0.067	0.083	1.70	2.10	
F	0.018	0.024	0.45	0.60	
G	0.0004	0.006	0.01	0.15	
H	0.035	0.043	0.90	1.10	
J	0.003	0.007	0.08	0.18	
K	0.012	0.020	0.30	0.51	
L	0.007	0.020	0.20	0.50	

Suggested Solder Pad Layout



ELECTRICAL CHARACTERISTICS (Ta=25℃ unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=250μA	60			V
Gate-Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250μA	1.0	1.5	2.5	V
Gate-Body Leakage	I_{GSS}	V_{DS} =0V, V_{GS} =±20V			±10	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} =60V, V_{GS} =0V			80	nA
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=300mA		1.2	2.5	Ω
		V_{GS}=4.5V, I_D=200mA		1.3	3.0	
Forward Transconductance	g_{fs}	V_{DS}=10V, I_D=200mA	80			ms
Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=300mA			1.2	V
Diode Forward Current	I_S				340	mA
Static Characteristics						
Input Capacitance	C_{iss}	V_{DS}=25V,V_{GS}=0V, f=1MHz		35		pF
Output Capacitance	C_{oss}			5		
Reverse Transfer Capacitance	C_{rss}			4		
Reverse Recovrey Charge	Q_{rr}	I_F=0.34A,di/dt=100A/us		8.5		nC
Reverse Recovery Time	t_{rr}			8		ns
Total Gate Charge	Q_g	V_{DS}=30V,V_{GS}=10V , I_D=0.34A		1.7		nC
Gate-Source Charge	Q_{gs}			0.5		
Gate-Drain Charge	Q_{gd}			0.3		
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=30V,V_{GS}=10V, I_D=340mA,R_{GEN}=6Ω		0.9		ns
Turn-on Rise Time	t_r			15		
Turn-off Delay Time	$t_{d(off)}$			4.5		
Turn-off fall Time	t_f			33		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

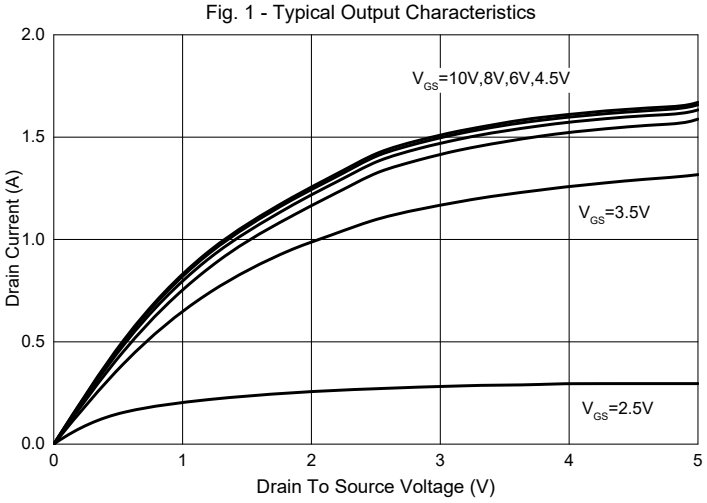


Fig. 2 - Transfer Characteristics

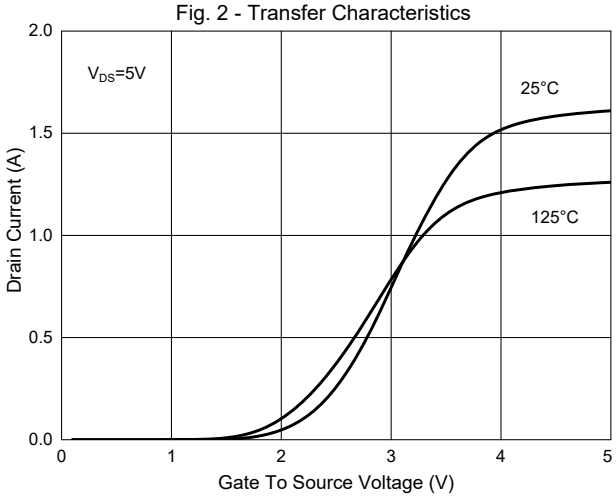


Fig.3 - NormalizedOnResistanceCharacteristics

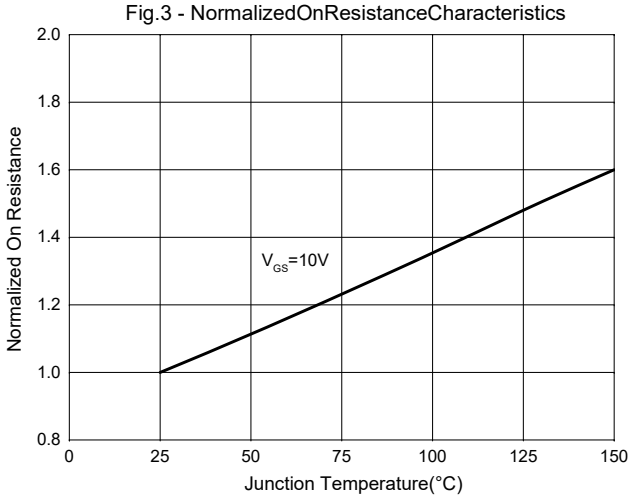


Fig. 4 - $R_{DS(ON)}$—I_D

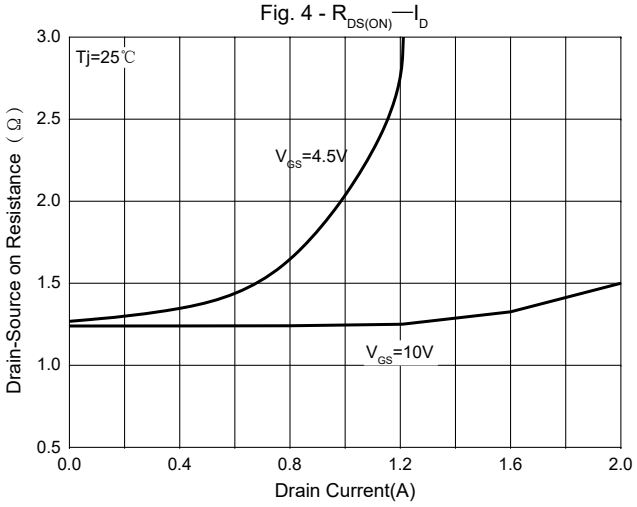


Fig. 5 - GateCharge

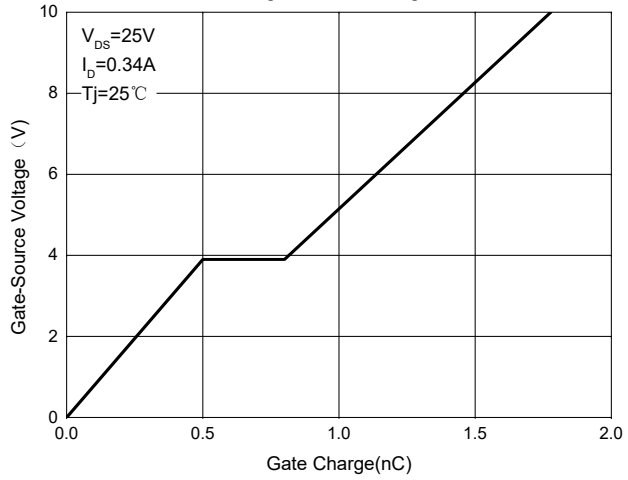
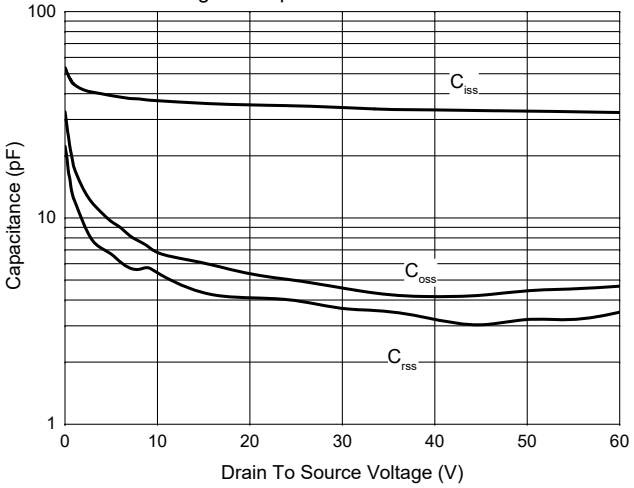


Fig. 6 - Capacitance Characteristics



Curve Characteristics

Fig. 7 - I_S—V_{SD}

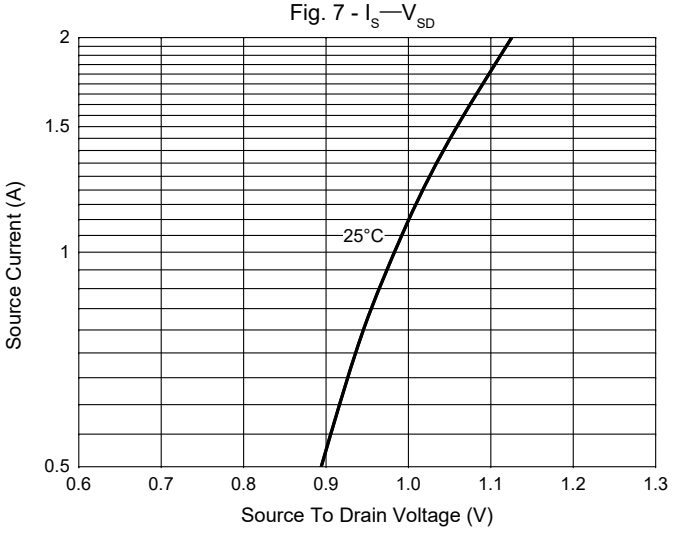


Fig. 8 - Safe Operation Area

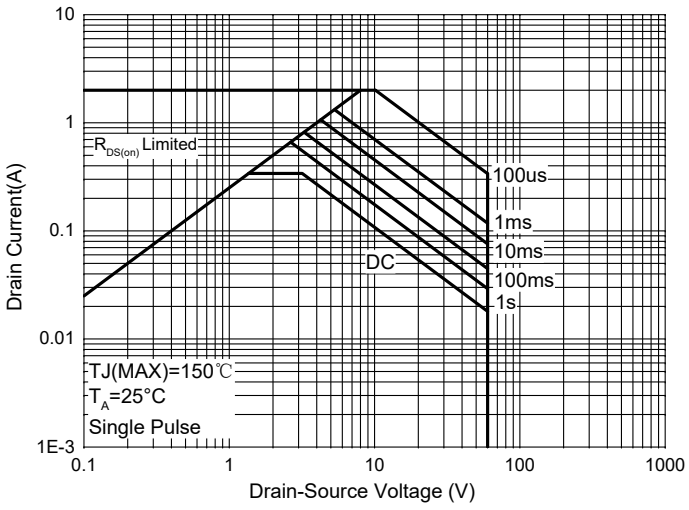
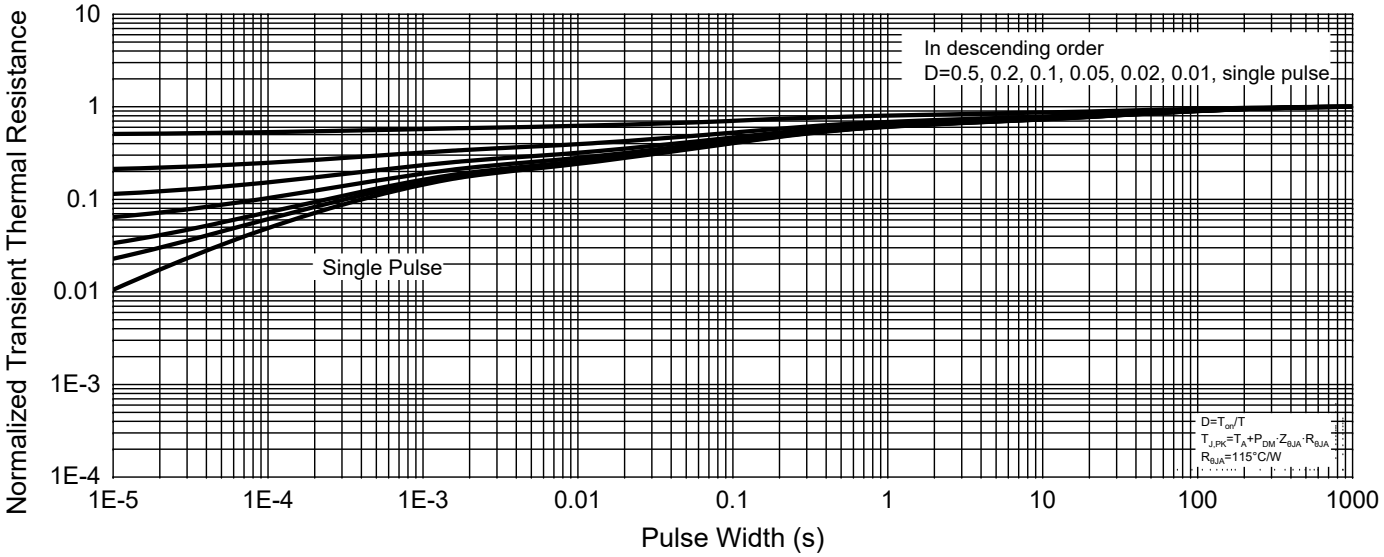


Fig. 9 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:3Kpcs/Reel